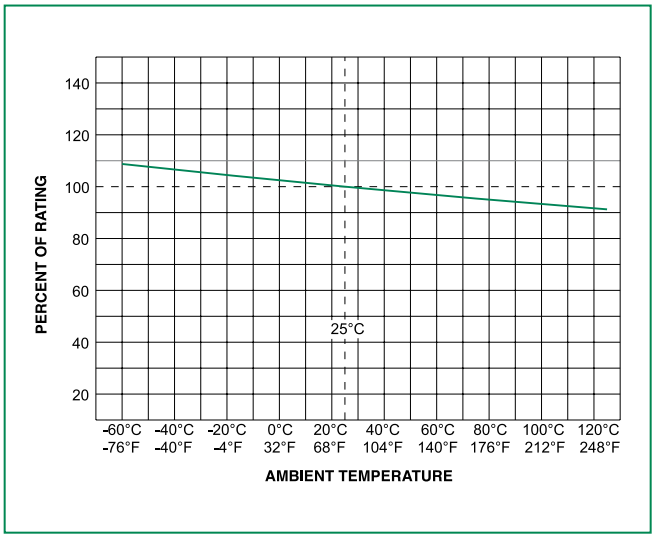
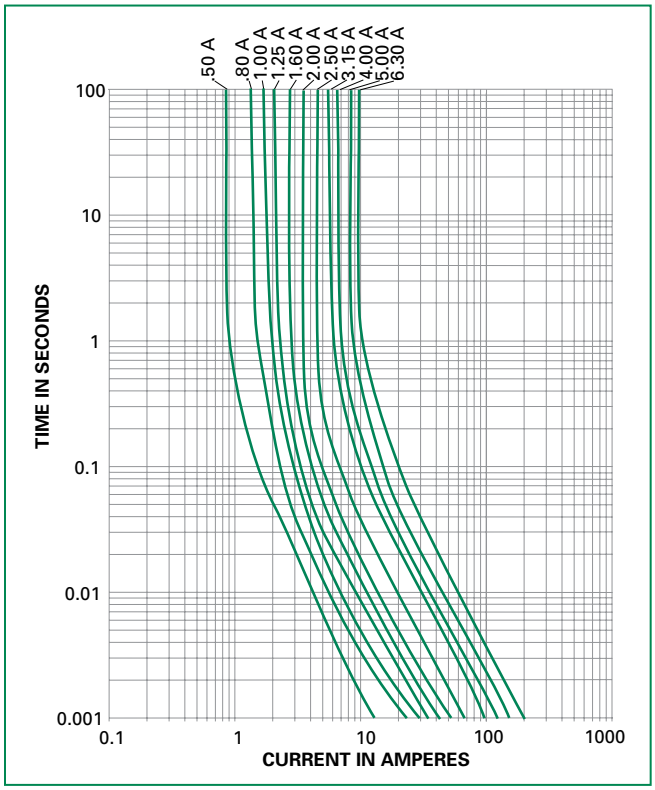
Temperature Re-rating Curve



Note:

1. Rerating depicted in this curve is in addition to the standard derating of 15% for continuous operation.

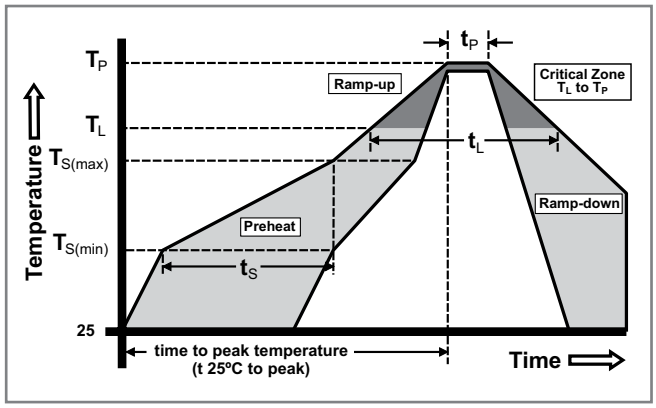
Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	-Temperature Min ($T_{s(min)}$)	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	-Time (Min to Max) (t_s)	60 – 120 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		5°C/second max.
$T_{S(max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Temperature (t_L)	60 – 90 seconds
Peak Temperature (T_P)		$260^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T_P)		8 minutes max.
Do not exceed		260°C

Wave Soldering Parameters	260°C Peak Temperature, 10 seconds max.



Revised: 06/21/15

Surface Mount Fuses

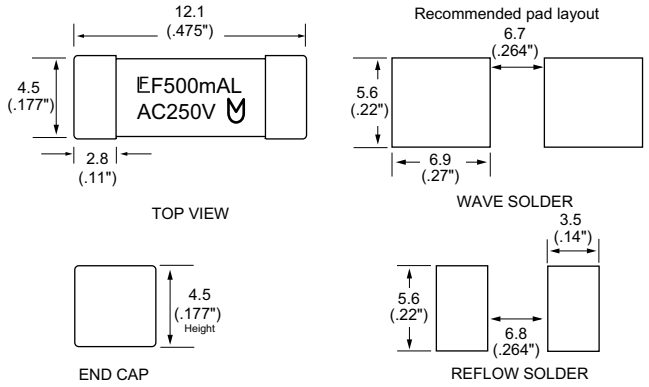
NANO2® > 250V UMF > Fast-Acting Fuse > 464 Series

Product Characteristics

Materials	Body: Ceramic Terminations: Silver-plated Caps
Product Marking	Brand, Ampere Rating, Voltage Rating, UMF Logo
Operating Temperature	-55°C to 125°C
Moisture Sensitivity Level	Level 1, J-STD-020
Solderability	IEC 60127-4
Insulation Resistance (after Opening)	IEC 60127-4 (0.1Mohm min @ 500VDC)

Thermal Shock	MIL-STD-202, Method 107, Test Condition B, 5 cycles, -65°C / +125°C
Mechanical Shock	MIL-STD-202, Method 213, Test Condition A
Vibration	MIL-STD-202, Method 201 (10-55 Hz)
Moisture Resistance	MIL-STD-202, Method 106, 10 cycles
Salt Spray	MIL-STD-202, Method 101, Test Condition B (48hrs)
Resistance to Soldering Heat	IEC 60127-4

Dimensions



Part Numbering System

0464 001. D R

SERIES

AMP Code*
Refer to Electrical Characteristics table

QUANTITY Code
D = 1500 pcs

PACKAGING Code
R = Tape and Reel

***Example:**
2.5 amp product is 0464**02.5** DR
(1 amp product shown above).

Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
24mm Tape and Reel	EIA RS-481-1 (IEC 286, part 3)	1500	DR

Revised: 06/21/15